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April 27, 2023

Rep. Susan McLain, Co-Chair, Joint Ways & Means, Education Subcommittee  
Senator Lew Frederick, Co-Chair, Joint Ways & Means, Education Subcommittee  
Oregon Legislative Assembly  
Salem, OR 97301

Dear Rep. McLain and Senator Frederick,

On behalf of HP, Inc. and our dedicated Corvallis campus employees, I'm writing to ask you to please continue the funding for the state university Engineering Technology Sustaining Funds (ETSF) at the level requested by the universities' current service level, 8.67 percent, or roughly \$31.489 million.

ESTF funding is contained in HB 5025, the Higher Education Coordinating Commission budget bill.

Over the years we have worked collaboratively with our trusted colleagues at Oregon State University, and it is programs like these that are critical to serving higher education and businesses that rely on a well-educated and trained engineering work force.

Since 1997, ETSF has made investments in STEM which have provided higher education institutions with continued growth in both the capacity and diversity of their programs.

Oregon's essential investment in the Engineering Technology Sustaining Fund has:

- Tripled the number of engineering graduates in the state.
- More than tripled research expenditures.
- Provided substantial economic mobility for students graduating with engineering degrees.
- Leveraged private donor and industry philanthropic support.

Obtaining an engineering degree remains one of the best options for economic mobility and a reduction in funding to the ETSF would significantly reduce Oregon student's

accessibility to these programs. With a decrease in state investment, engineering programs could become more costly, create fewer degree options, reduce the number of instructors and courses available, increase class sizes and ultimately produce fewer qualified engineers and scientists that could be essential to Oregon's economic recovery from the COVID pandemic.

Our HP Corvallis campus, which employs more than 1,000 professionals, is the "technology mothership" for our printing businesses, including microfluids research.

The work at our Corvallis campus has made HP is an industry leader, and the excellent work at OSU has meant that we can directly benefit with well - educated and trained engineers, many of whom are women.

We urge you to please protect this crucial fund which has become the foundation for creating successful engineers in the state of Oregon.

Sincerely,

A handwritten signature in black ink, appearing to read "Tim Weber". The signature is written in a cursive style with a large initial "T" and "W".

Dr. Tim Weber  
Head of 3D Materials R&D – HP Inc.

CC: Speaker Dan Rayfield  
Senator Sara Gelsner Blouin